

Features

- $BV_{CEO} > 45V$
- $I_C = 100mA$ High Collector Current
- $P_D = 925mW$ Power Dissipation
- 0.36mm² Package Footprint, 40% Smaller than DFN1006
- 0.4mm Height Package Minimizing Off-Board Profile
- Complementary PNP Type BC857BZ
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- Halogen and Antimony Free. "Green" Device (Note 3)

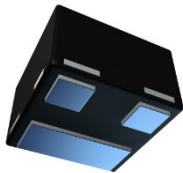
Mechanical Data

- Case: X2-DFN0606-3
- Case Material: Molded Plastic, "Green" Molding Compound, UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish — NiPdAu, Solderable per MIL-STD-202, Method 208(e4)
- Weight: 0.0008 grams (Approximate)

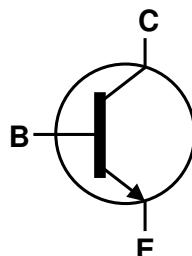
X2-DFN0606-3



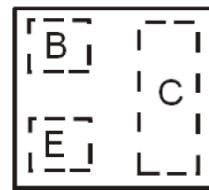
Top View



Bottom View



Device Symbol


 Top View
 Device Schematic

Ordering Information (Note 4)

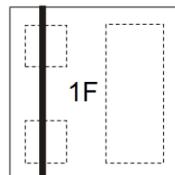
Product	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
BC847BFZ-7B	1F	7	8mm	10,000

Notes:

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information

X2-DFN0606-3



1F = Product Type Marking Code

Top View
 Bar Denotes Base
 and Emitter Side

Absolute Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	50	V
Collector-Emitter Voltage	V_{CEO}	45	V
Emitter-Base Voltage	V_{EBO}	6.0	V
Continuous Collector Current	I_C	100	mA
Peak Pulse Collector Current	I_{CM}	200	mA

Thermal Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation	P_D	270	mW
(Note 5)	(Note 6)	925	
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	465	°C/W
(Note 5)	(Note 6)	135	
Thermal Resistance, Junction to Lead	$R_{\theta JL}$	135	°C/W
Operating and Storage and Temperature Range	T_J, T_{STG}	-55 to +150	°C

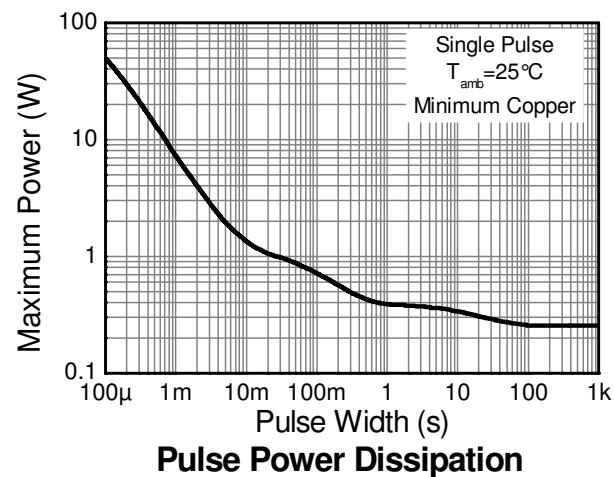
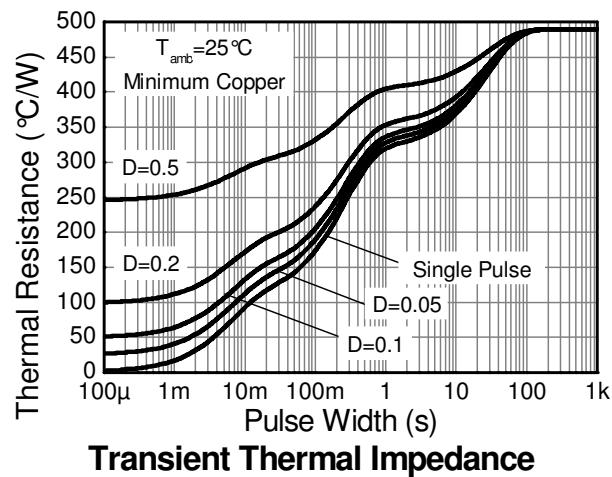
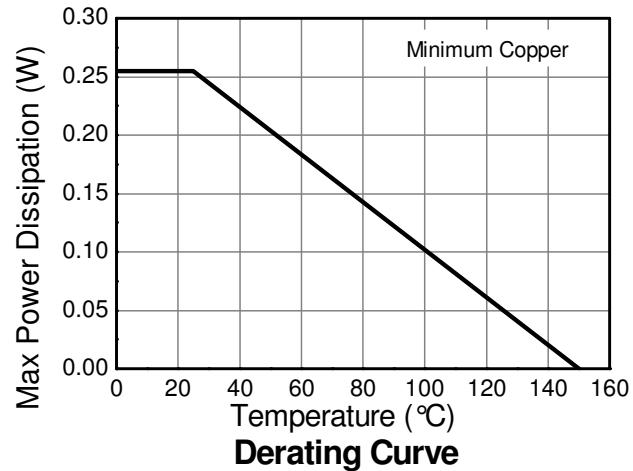
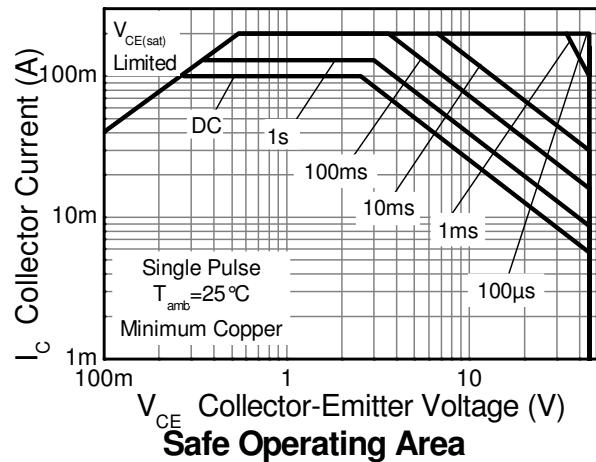
ESD Ratings (Note 8)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	200	V	B

Notes:

5. For the device mounted on minimum recommended pad layout 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in steady state condition. The entire exposed collector pad is attached to the heatsink.
6. Same as Note 5, except the exposed collector pad is mounted on 25mm x 25mm 2oz copper.
7. Thermal resistance from junction to solder-point (on the exposed collector pad).
8. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

Thermal Characteristics and Derating Information



Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Typical	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Collector-Base Breakdown Voltage	BV_{CBO}	50	150	—	V	$I_C = 50\mu\text{A}, I_B = 0$
Collector-Emitter Breakdown Voltage	BV_{CES}	50	150	—	—	$I_C = 50\mu\text{A}, I_B = 0$
Collector-Emitter Breakdown Voltage (Note 9)	BV_{CEO}	45	65	—	V	$I_C = 1\text{mA}, I_B = 0$
Collector-Base Breakdown Voltage	BV_{EBO}	6.0	8.35	—	V	$I_E = 50\mu\text{A}, I_C = 0$
Collector-Base Cutoff Current	I_{CBO}	—	—	15	nA	$V_{\text{CB}} = 40\text{V}$
Collector-Emitter Cutoff Current	I_{CES}	—	—	15	nA	$V_{\text{CE}} = 40\text{V}$
ON CHARACTERISTICS (Note 9)						
DC Current Gain	h_{FE}	— 200	220 260	— 470	—	$I_C = 10\mu\text{A}, V_{\text{CE}} = 5.0\text{V}$ $I_C = 2.0\text{mA}, V_{\text{CE}} = 5.0\text{V}$
Collector-Emitter Saturation Voltage	$V_{\text{CE}(\text{sat})}$	—	50 122	125 300	mV	$I_C = 10\text{mA}, I_B = 0.5\text{mA}$ $I_C = 100\text{mA}, I_B = 5.0\text{mA}$
Base-Emitter Saturation Voltage	$V_{\text{BE}(\text{sat})}$	—	760 880	1,000 1,100	mV	$I_C = 10\text{mA}, I_B = 0.5\text{mA}$ $I_C = 100\text{mA}, I_B = 5.0\text{mA}$
Base-Emitter Voltage	$V_{\text{BE}(\text{on})}$	580	650 —	750 800	mV	$I_C = 2.0\text{mA}, V_{\text{CE}} = 5\text{V}$ $I_C = 10\text{mA}, V_{\text{CE}} = 5\text{V}$
SMALL SIGNAL CHARACTERISTICS						
Output Capacitance	C_{obo}	—	1.3	—	pF	$V_{\text{CB}} = 10.0\text{V}, f = 1.0\text{MHz}, I_E = 0$
Current Gain-Bandwidth Product	f_T	100	180	—	MHz	$V_{\text{CE}} = 5\text{V}, I_C = 10\text{mA}, f = 100\text{MHz}$

Note: 9. Measured under pulsed conditions. Pulse width $\leq 300\mu\text{s}$. Duty cycle $\leq 2\%$.

Typical Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

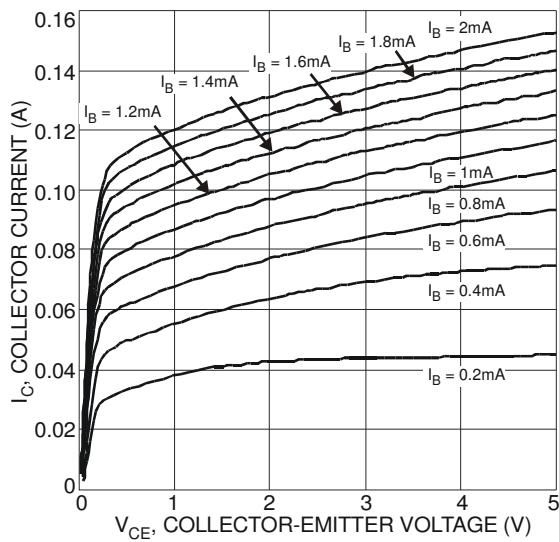


Fig. 4 Typical Collector Current vs. Collector-Emitter Voltage

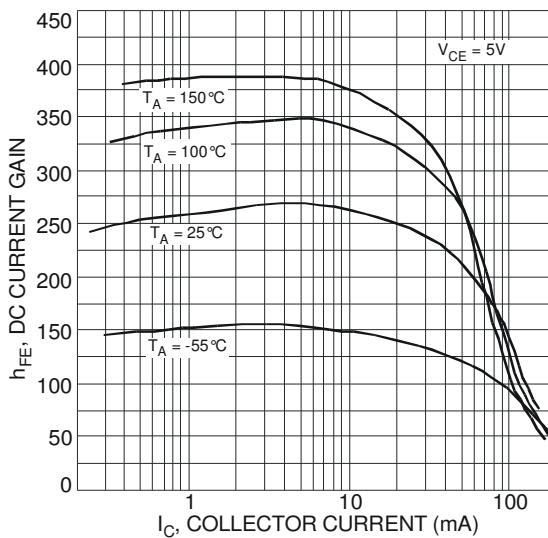


Fig. 5 Typical DC Current Gain vs. Collector Current

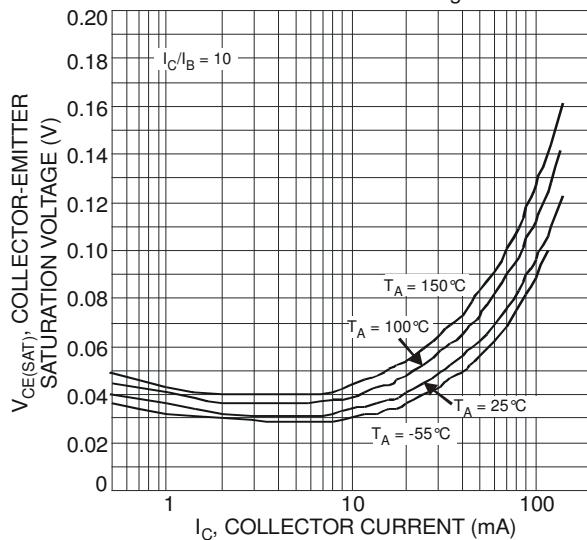


Fig. 6 Typical Collector-Emitter Saturation Voltage vs. Collector Current

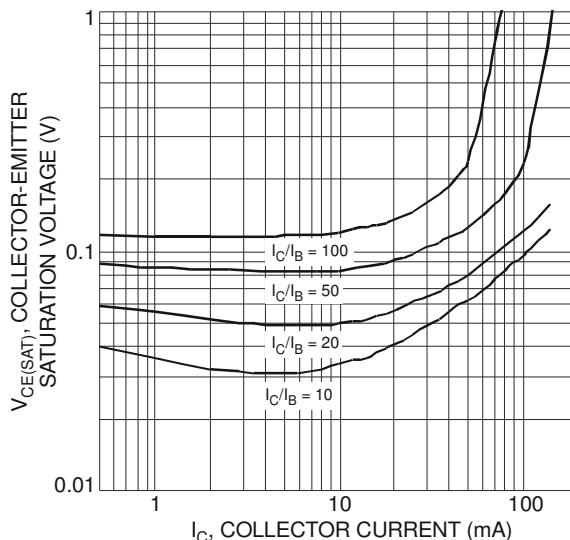


Fig. 7 Typical Collector-Emitter Saturation Voltage vs. Collector Current

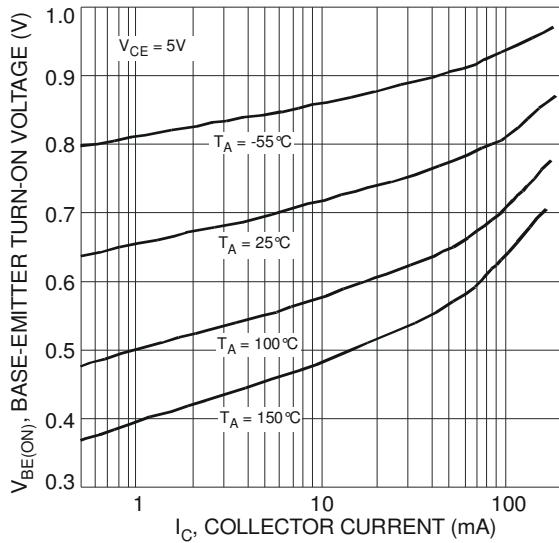


Fig. 8 Typical Base-Emitter Turn-On Voltage vs. Collector Current

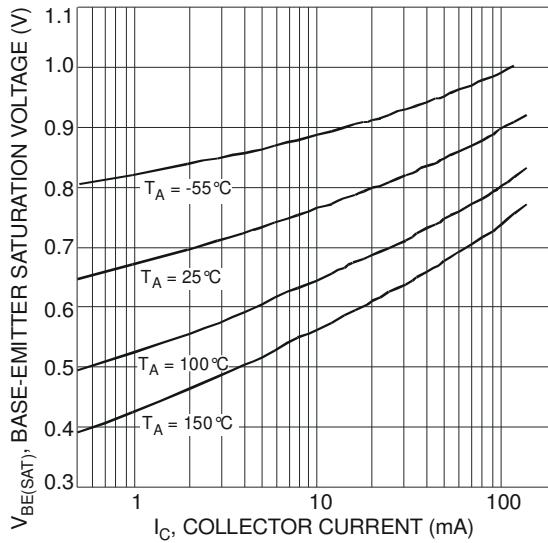
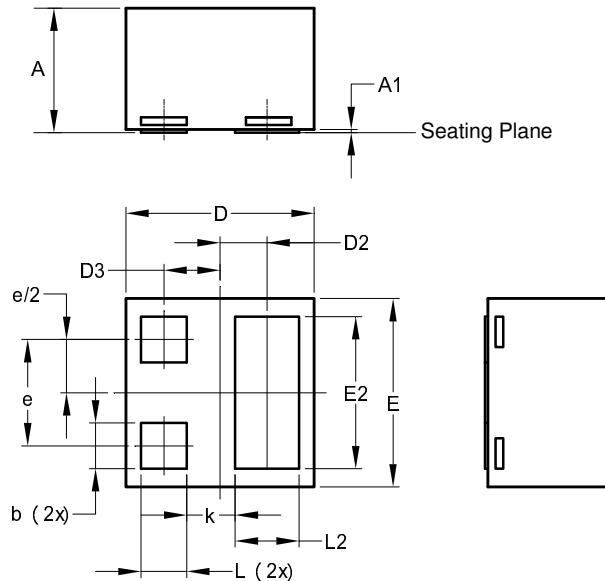


Fig. 9 Typical Base-Emitter Saturation Voltage vs. Collector Current

Package Outline Dimensions

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.

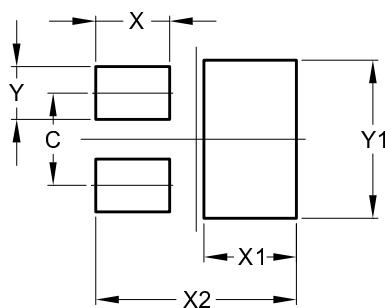


X2-DFN0606-3			
Dim	Min	Max	Typ
A	0.36	0.42	0.39
A1	0	0.05	0.02
b	0.10	0.20	0.15
D	0.57	0.67	0.62
D2	0.155 BSC		
D3	0.185 BSC		
E	0.57	0.67	0.62
E2	0.40	0.60	0.50
e	0.35 BSC		
k	0.16 REF		
L	0.09	0.21	0.15
L2	0.11	0.31	0.21

All Dimensions in mm

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	0.350
X	0.280
X1	0.350
X2	0.760
Y	0.200
Y1	0.600

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